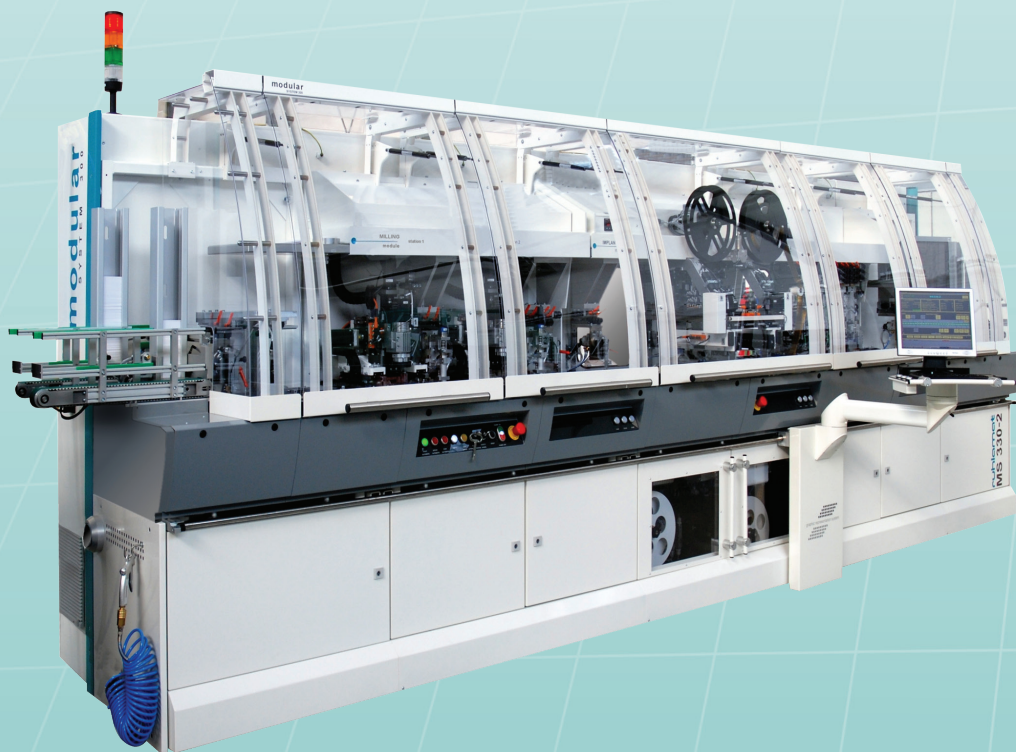


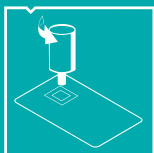
Smart card – combination milling & implanting



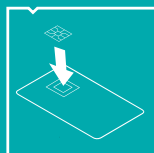
MS330-2

The combination machine MS330-2 is used for high speed cavity milling, IC module testing and encoding if required.

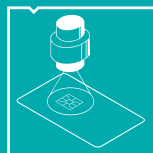
Cavities can be designed easily by means of the sophisticated software program "Easy Create". The modular standard configuration consists of a high speed milling module with cleaning station and a high speed pick and place system for modules.



milling



implanting



optical inspection

Different punching tools can be adapted for modules on 535mm tape.

The MS330-2 can be configured also for dual interface cards using antenna recognition and functionality test units as option. Different kind of connection technologies can be implemented using hot or cold liquid and conductive glue application stations. Tacking, hot press and cold press station are included in the standard MS330-2 configuration.

Several standard and optional quality improvement stations guarantee high-quality production.

Smart card – combination milling & implanting

Applications

- high speed application for automatic milling of cavities in smart cards according ISO 7816 combined with automatic chip module implanting into cavities of card bodies
- automatic punching out modules from reel and transfer system
- telephone cards, dual interface cards (DIF), GSM cards, ID cards, etc.

Benefits & features

- combines optimum proportion of standardizing with highest level of individuality by upgradable customized design, modular system
- exchange magazine with 500 cards capacity, card orientation control
- card image analysis; automatic card thickness, cavity depth control
- special software tool "Easy Create" for creation of new cavities
- antenna recognition system with functionality test (DIF)
- different gluing methods possible
- module position control
- comfortable windows based operator software for easy handling
- assure highest level of quality
- additional chip module testing and personalisation of telephone cards can be integrated
- tele diagnostic service

Technical specifications

card material:

- PVC, PC, ABS, PET-G and other materials upon request
- card dimensions according to format ID-1

tape specification:

- module tape: 35mm; pitch 9.5 or 14.25
- spacer tape: 35mm
- reel dimension: for modul tape and protection tape max 530mm (larger size on request)
- Standard and FCOS - modules

IC module types:

- processor modules
- memory modules
- contactless and dual interface applications upon request

facilities:

- compressed air: 6 bar, oil-free, dry
- electrical supply: 3 x 400V, 50 Hz (other's possible), 5 kW

environmental conditions:

- ambient temperature: 22°C ± 5°
- degree of relative humidity: max. 70%

machine dimensions (basic configuration):

- height: 1,950 mm
- length: 5,400 mm
- width: 1,400 mm
- weight: 4,300 kg

throughput:

- exceeding 4,000 cph
- depending on application and specification